

AMENDMENTS TO THE SPECIFICATION (INCLUDING ABSTRACT)

Without prejudice, please amend the Abstract as below:

~~Methods and systems for heat treating a workpiece are disclosed. One such~~
A method involves pre-heating ~~the a~~ workpiece to an intermediate temperature, heating a surface of the workpiece to a desired temperature greater than the intermediate temperature, and enhancing cooling of the workpiece. Enhancing cooling may involve absorbing radiation thermally emitted by the workpiece. ~~Semiconductor heating methods and apparatuses are also disclosed. One such~~ An apparatus includes a first heating source for heating a first surface of a semiconductor wafer, a second heating source for heating a second surface of the semiconductor wafer, and a first cooled window disposed between the first heating source and the semiconductor wafer.